



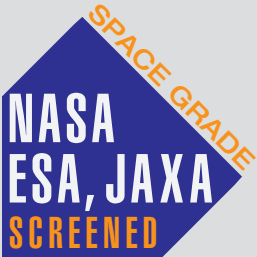
SERIES 77
Heat Shrink Boots



Compound Material Specifications
Type 8 Material: 2008 Space Grade, Low Outgassing

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GTS 4123: Heat-Shrinkable, Space Grade, Fluoropolymer Alloy
Operating Temperature Range: -50°C to 175°C



This Material Specification establishes the quality standard for a heat-shrinkable compound used to manufacture Glenair® molded components. These components meet the low out-gassing NASA TML and CVCM outgassing requirements and area suitable for high altitude and space applications. Dimensions of molded shapes are specified in the relevant SCD. All testing to be carried out on molded sheets 2mm thick unless otherwise specified. Recommended adhesive for Type 8 is the two-part epoxy Glenair 779-001.

Installation Temperature: Minimum 135°C, Recovered 175°C

Compound 2008 Type 8 - Materials Specification		
Test	Test Procedure	Test Requirement
Visual Examination		Homogenous and essentially free from pinholes, bubbles, flaws, cracks and inclusions, color is black
Tensile Strength	IEC 62329-2	12 MPa minimum
Ultimate Elongation	IEC 62329-2	300% minimum
2% Secant Modulus	IEC 62329-2	100-125MPa
Specific Gravity	IEC 62329-2	<1.4
Heat Shock 4hrs at 225°C	IEC 62329-2	No dripping or cracking
Heat Aging 168hrs at 175°C	IEC 62329-2	Tensile strength 10.0 MPa minimum Ultimate elongation 200% minimum No Dripping, flow or cracking
Low Temperature Flexibility 4hrs at -50°C	MIL-DTL-85049	No cracking
Flammability	IEC 62329-2	Time of burning < 60secs Length of burning <25mm
Water Absorption 24hrs at 23°C	IEC 62329-2	0.5% maximum
Electric Strength	IEC 62329-2	8 MV/m minimum
Volume Resistivity	IEC 62329-2	10 ¹² ohms cms minimum
Outgassing	ASTM E595	CVCM <0.1% TML <1%

Listed in the NASA MAPTIS (Material and Process Technical Information System) database
NASA MAPTIS Registered, material code 09719